



Sikama’s EA UP1200, developed in conjunction with AirProducts using Electron Attachment technology, provides truly residue-free fluxless soldering without the use of formic acid or other harmful chemicals.

This revolutionary breakthrough offers the safest and lowest cost per wafer yet for the semiconductor packaging industry.

	SIKAMA ELECTRON ATTACHMENT UP1200	FORMIC ACID COMPETITION
WAFER THROUGHPUT		
CHEMICAL COST		
GAS COST		
POST PROCESS RESIDUE		
EQUIPMENT COST		
POWER CONSUMPTION		
MAINTENANCE COST		
ENVIRONMENTAL HAZARD		
HEALTH HAZARD		
SAFETY		
TOTAL COST PER WAFER		

To learn more about this exciting technology, contact Sikama at sales@sikama.com, or AirProducts at arslangk@airproducts.com